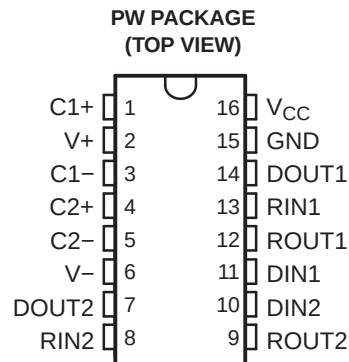


3-V TO 5.5-V MULTICHANNEL RS-232 LINE DRIVER/RECEIVER WITH ± 15 -kV IEC ESD PROTECTION

FEATURES

- Qualified for Automotive Applications
- Meets or Exceeds the Requirements of TIA/EIA-232-F and ITU v.28 Standards
- Operates With 3-V to 5.5-V V_{CC} Supply
- Operates up to 250 kbit/s
- Two Drivers and Two Receivers
- Low Standby Current . . . 300 μ A Typical
- External Capacitors . . . $4 \times 0.1 \mu$ F
- Accepts 5-V Logic Input With 3.3-V Supply
- Pin Compatible to Alternative High-Speed Pin-Compatible Device (1 Mbit/s): SNx5C3232



DESCRIPTION

The MAX3232E device consists of two line drivers, two line receivers, and a dual charge-pump circuit with ± 15 -kV IEC ESD protection pin to pin (serial-port connection pins, including GND). The device meets the requirements of TIA/EIA-232-F and provides the electrical interface between an asynchronous communication controller and the serial-port connector. The charge pump and four small external capacitors allow operation from a single 3-V to 5.5-V supply. The device operates at data signaling rates up to 250 kbit/s and a maximum of 30-V/ μ s driver output slew rate.

ORDERING INFORMATION⁽¹⁾

T_A	PACKAGE ⁽²⁾		ORDERABLE PART NUMBER	TOP-SIDE MARKING
-40°C to 85°C	TSSOP – PW	Reel of 2000	MAX3232EIPWRQ1	MB3232I

- (1) For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI web site at www.ti.com.
 (2) Package drawings, thermal data, and symbolization are available at www.ti.com/packaging.

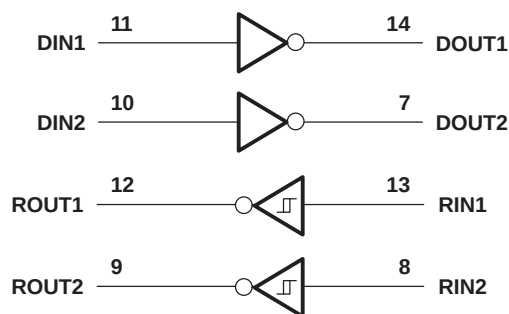
FUNCTION TABLE

EACH DRIVER ⁽¹⁾		EACH RECEIVER ⁽¹⁾	
INPUT DIN	OUTPUT DOUT	INPUT RIN	OUTPUT ROUT
L	H	L	H
H	L	H	L
		Open	H

- (1) H = high level, L = low level, Open = input disconnected or connected driver off



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

LOGIC DIAGRAM (POSITIVE LOGIC)**ABSOLUTE MAXIMUM RATINGS**over operating free-air temperature range (unless otherwise noted) ⁽¹⁾

		VALUE	UNIT
V _{CC}	Supply voltage range ⁽²⁾	–0.3 to 6	V
V+	Positive output supply voltage range ⁽²⁾	–0.3 to 7	V
V–	Negative output supply voltage range ⁽²⁾	0.3 to –7	V
V+ – V–	Supply voltage difference ⁽²⁾	13	V
V _I	Input voltage range	Drivers	–0.3 to 6
		Receivers	–25 to 25
V _O	Output voltage range	Drivers	–13.2 to 13.2
		Receivers	–0.3 to V _{CC} + 0.3
θ _{JA}	Package thermal impedance ⁽³⁾ ⁽⁴⁾	108	°C/W
T _J	Operating virtual junction temperature	150	°C
T _{stg}	Storage temperature range	–65 to 150	°C

- (1) Stresses beyond those listed under *absolute maximum ratings* may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under *recommended operating conditions* is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) All voltages are with respect to network GND.
- (3) Maximum power dissipation is a function of T_J(max), θ_{JA}, and T_A. The maximum allowable power dissipation at any allowable ambient temperature is P_D = (T_J(max) – T_A)/θ_{JA}. Operating at the absolute maximum T_J of 150°C can affect reliability.
- (4) The package thermal impedance is calculated in accordance with JESD 51-7.

RECOMMENDED OPERATING CONDITIONS⁽¹⁾see [Figure 4](#)

			MIN	NOM	MAX	UNIT
Supply voltage		V _{CC} = 3.3 V	3	3.3	3.6	V
		V _{CC} = 5 V	4.5	5	5.5	
V _{IH}	Driver high-level input voltage	DIN	V _{CC} = 3.3 V		5.5	V
			V _{CC} = 5 V		5.5	
V _{IL}	Driver low-level input voltage	DIN	0		0.8	V
V _I	Receiver input voltage		–25		25	V
T _A	Operating free-air temperature	MAX3232I	–40		85	°C

- (1) Test conditions are C1–C4 = 0.1 μF at V_{CC} = 3.3 V ±0.3 V; C1 = 0.047 μF, C2–C4 = 0.33 μF at V_{CC} = 5 V ±0.5 V.

ELECTRICAL CHARACTERISTICS

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see [Figure 4](#))

PARAMETER	TEST CONDITIONS ⁽¹⁾	MIN	TYP ⁽²⁾	MAX	UNIT
I_{CC} Supply current	No load, $V_{CC} = 3.3\text{ V}$ or 5 V		0.3	1	mA

(1) Test conditions are $C1-C4 = 0.1\text{ }\mu\text{F}$ at $V_{CC} = 3.3\text{ V} \pm 0.3\text{ V}$; $C1 = 0.047\text{ }\mu\text{F}$, $C2-C4 = 0.33\text{ }\mu\text{F}$ at $V_{CC} = 5\text{ V} \pm 0.5\text{ V}$.

(2) All typical values are at $V_{CC} = 3.3\text{ V}$ or $V_{CC} = 5\text{ V}$ and $T_A = 25^\circ\text{C}$.

DRIVER SECTION – ELECTRICAL CHARACTERISTICS

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see [Figure 4](#))

PARAMETER	TEST CONDITIONS ⁽¹⁾	MIN	TYP ⁽²⁾	MAX	UNIT
V_{OH} High-level output voltage	DOOUT at $R_L = 3\text{ k}\Omega$ to GND, DIN = GND	5	5.4		V
V_{OL} Low-level output voltage	DOOUT at $R_L = 3\text{ k}\Omega$ to GND, DIN = V_{CC}	–5	–5.4		V
I_{IH} High-level input current	$V_I = V_{CC}$		± 0.01	± 1	μA
I_{IL} Low-level input current	V_I at GND		± 0.01	± 1	μA
I_{OS} Short-circuit output current ⁽³⁾	$V_{CC} = 3.6\text{ V}$, $V_O = 0\text{ V}$		± 35	± 60	mA
	$V_{CC} = 5.5\text{ V}$, $V_O = 0\text{ V}$				
r_o Output resistance	V_{CC} , V^+ , and $V^- = 0\text{ V}$, $V_O = 2\text{ V}$	300	10M		Ω

(1) Test conditions are $C1-C4 = 0.1\text{ }\mu\text{F}$ at $V_{CC} = 3.3\text{ V} \pm 0.3\text{ V}$; $C1 = 0.047\text{ }\mu\text{F}$, $C2-C4 = 0.33\text{ }\mu\text{F}$ at $V_{CC} = 5\text{ V} \pm 0.5\text{ V}$.

(2) All typical values are at $V_{CC} = 3.3\text{ V}$ or $V_{CC} = 5\text{ V}$ and $T_A = 25^\circ\text{C}$.

(3) Short-circuit durations should be controlled to prevent exceeding the device absolute power-dissipation ratings, and not more than one output should be shorted at a time.

DRIVER SECTION – SWITCHING CHARACTERISTICS

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see [Figure 4](#))

PARAMETER	TEST CONDITIONS ⁽¹⁾	MIN	TYP ⁽²⁾	MAX	UNIT
Maximum data rate	$C_L = 1000\text{ pF}$, One DOOUT switching, $R_L = 3\text{ k}\Omega$, See Figure 1	150	250		kbit/s
$t_{sk(p)}$ Pulse skew ⁽³⁾	$C_L = 150\text{ pF}$ to 2500 pF , $R_L = 3\text{ k}\Omega$ to $7\text{ k}\Omega$, See Figure 2		300		ns
SR(tr) Slew rate, transition region (see Figure 1)	$R_L = 3\text{ k}\Omega$ to $7\text{ k}\Omega$, $V_{CC} = 3.3\text{ V}$	$C_L = 150\text{ pF}$ to 1000 pF		30	v/ μs
		$C_L = 150\text{ pF}$ to 2500 pF	4	30	

(1) Test conditions are $C1-C4 = 0.1\text{ }\mu\text{F}$ at $V_{CC} = 3.3\text{ V} \pm 0.3\text{ V}$; $C1 = 0.047\text{ }\mu\text{F}$, $C2-C4 = 0.33\text{ }\mu\text{F}$ at $V_{CC} = 5\text{ V} \pm 0.5\text{ V}$.

(2) All typical values are at $V_{CC} = 3.3\text{ V}$ or $V_{CC} = 5\text{ V}$ and $T_A = 25^\circ\text{C}$.

(3) Pulse skew is defined as $|t_{PLH} - t_{PHL}|$ of each channel of the same device.

RECEIVER SECTION – ELECTRICAL CHARACTERISTICS

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see [Figure 4](#))

PARAMETER	TEST CONDITIONS ⁽¹⁾	MIN	TYP ⁽²⁾	MAX	UNIT
V_{OH} High-level output voltage	$I_{OH} = -1\text{ mA}$	$V_{CC} - 0.6\text{ V}$	$V_{CC} - 0.1\text{ V}$		V
V_{OL} Low-level output voltage	$I_{OL} = 1.6\text{ mA}$			0.4	V
V_{IT+} Positive-going input threshold voltage	$V_{CC} = 3.3\text{ V}$		1.5	2.4	V
	$V_{CC} = 5\text{ V}$		1.8	2.4	
V_{IT-} Negative-going input threshold voltage	$V_{CC} = 3.3\text{ V}$	0.6	1.2		V
	$V_{CC} = 5\text{ V}$	0.8	1.5		
V_{hys} Input hysteresis ($V_{IT+} - V_{IT-}$)			0.3		V
r_i Input resistance	$V_I = \pm 3\text{ V}$ to $\pm 25\text{ V}$	3	5	7	k Ω

(1) Test conditions are $C1-C4 = 0.1\text{ }\mu\text{F}$ at $V_{CC} = 3.3\text{ V} \pm 0.3\text{ V}$; $C1 = 0.047\text{ }\mu\text{F}$, $C2-C4 = 0.33\text{ }\mu\text{F}$ at $V_{CC} = 5\text{ V} \pm 0.5\text{ V}$.

(2) All typical values are at $V_{CC} = 3.3\text{ V}$ or $V_{CC} = 5\text{ V}$ and $T_A = 25^\circ\text{C}$.

RECEIVER SECTION – SWITCHING CHARACTERISTICS

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see [Figure 3](#))

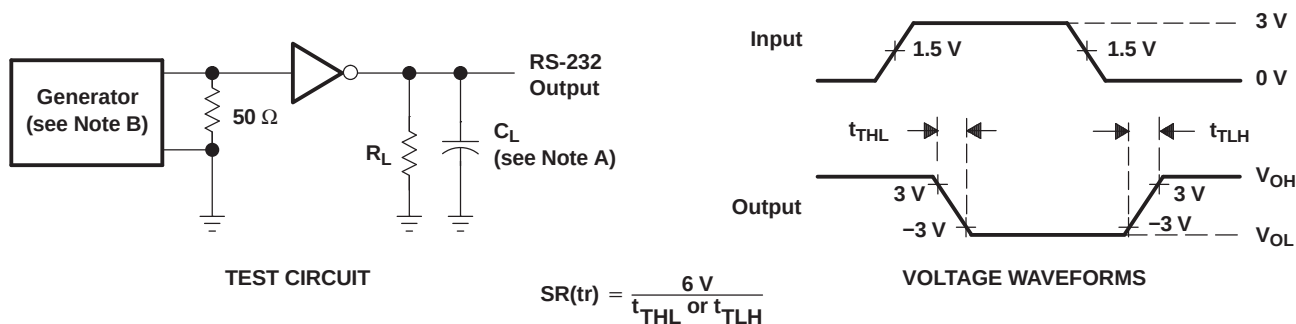
PARAMETER		TEST CONDITIONS ⁽¹⁾	TYP ⁽²⁾	UNIT
t_{PLH}	Propagation delay time, low- to high-level output	$C_L = 150 \text{ pF}$	300	ns
t_{PHL}	Propagation delay time, high- to low-level output	$C_L = 150 \text{ pF}$	300	ns
$t_{sk(p)}$	Pulse skew ⁽³⁾		300	ns

(1) Test conditions are $C1-C4 = 0.1 \text{ }\mu\text{F}$ at $V_{CC} = 3.3 \text{ V} \pm 0.3 \text{ V}$; $C1 = 0.047 \text{ }\mu\text{F}$, $C2-C4 = 0.33 \text{ }\mu\text{F}$ at $V_{CC} = 5 \text{ V} \pm 0.5 \text{ V}$.

(2) All typical values are at $V_{CC} = 3.3 \text{ V}$ or $V_{CC} = 5 \text{ V}$ and $T_A = 25^\circ\text{C}$.

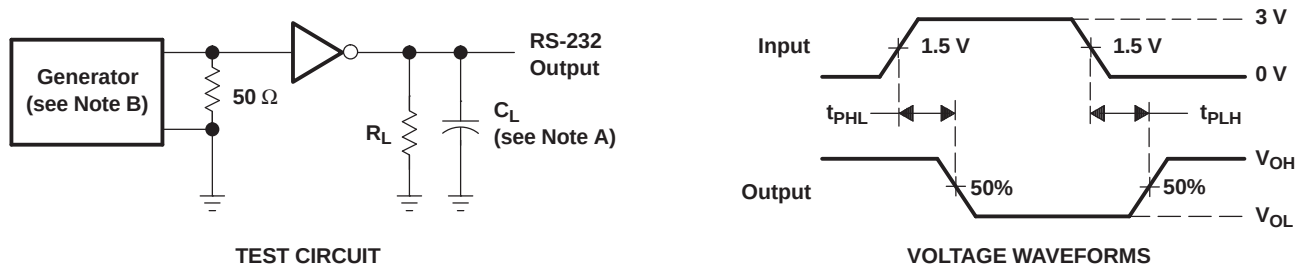
(3) Pulse skew is defined as $|t_{PLH} - t_{PHL}|$ of each channel of the same device.

PARAMETER MEASUREMENT INFORMATION



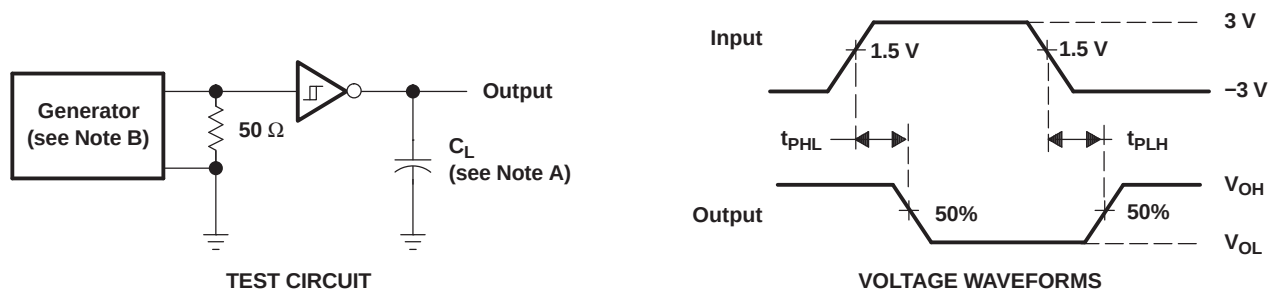
- A. C_L includes probe and jig capacitance.
- B. The pulse generator has the following characteristics: PRR = 250 kbit/s, $Z_O = 50\ \Omega$, 50% duty cycle, $t_r \leq 10\text{ ns}$, $t_f \leq 10\text{ ns}$.

Figure 1. Driver Slew Rate



- A. C_L includes probe and jig capacitance.
- B. The pulse generator has the following characteristics: PRR = 250 kbit/s, $Z_O = 50\ \Omega$, 50% duty cycle, $t_r \leq 10\text{ ns}$, $t_f \leq 10\text{ ns}$.

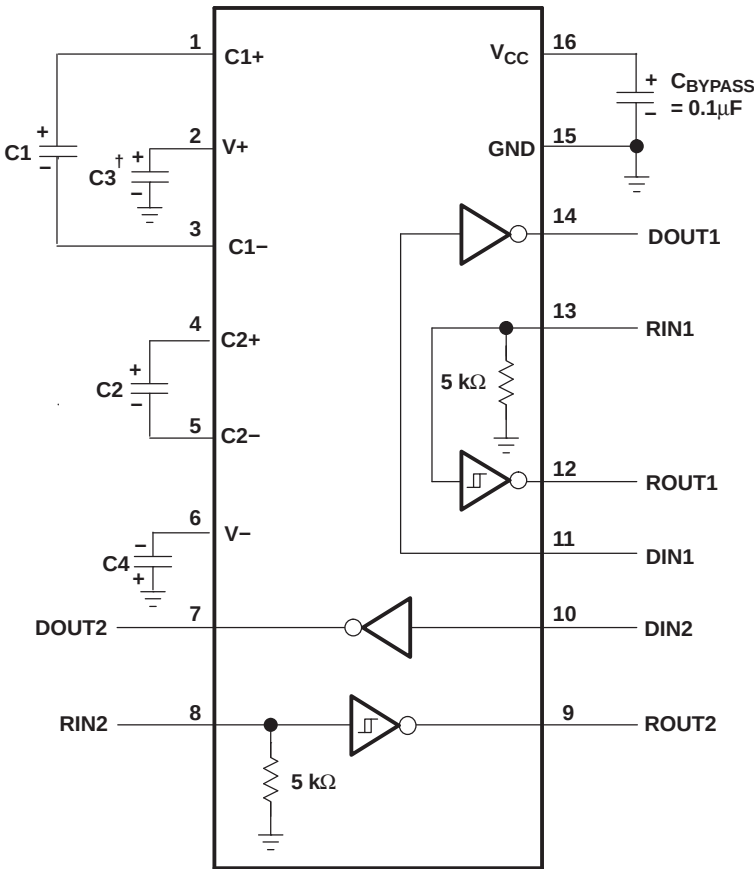
Figure 2. Driver Pulse Skew



- A. C_L includes probe and jig capacitance.
- B. The pulse generator has the following characteristics: $Z_O = 50\ \Omega$, 50% duty cycle, $t_r \leq 10\text{ ns}$, $t_f \leq 10\text{ ns}$.

Figure 3. Receiver Propagation Delay Times

APPLICATION INFORMATION



† C3 can be connected to V_{CC} or GND.

NOTES: A. Resistor values shown are nominal.

B. Nonpolarized ceramic capacitors are acceptable. If polarized tantalum or electrolytic capacitors are used, they should be connected as shown.

V_{CC} vs CAPACITOR VALUES

V _{CC}	C1	C2, C3, C4
3.3 V ± 0.3 V	0.1 μF	0.1 μF
5 V ± 0.5 V	0.047 μF	0.33 μF
3 V to 5.5 V	0.1 μF	0.47 μF

Figure 4. Typical Operating Circuit and Capacitor Values

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)	Op Temp (°C)	Top-Side Markings (4)	Samples
MAX3232EIPWRQ1	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	MB3232I	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) Only one of markings shown within the brackets will appear on the physical device.

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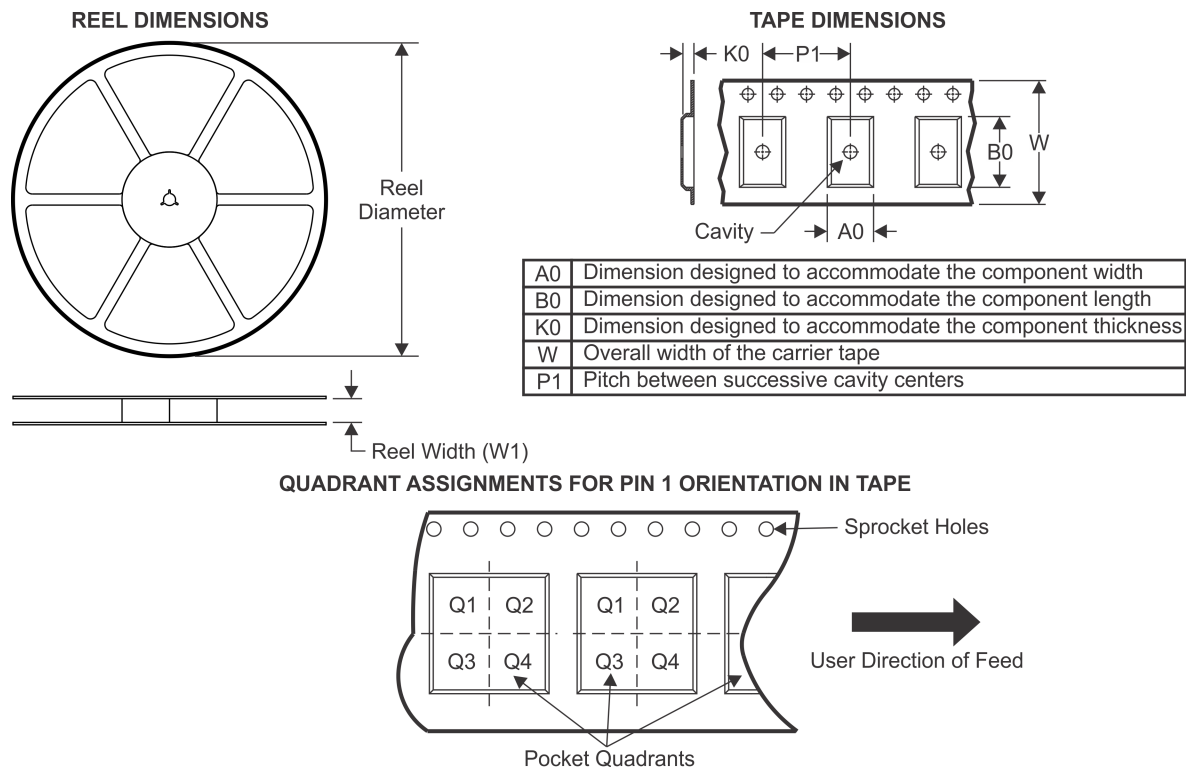
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OTHER QUALIFIED VERSIONS OF MAX3232E-Q1 :

- Catalog: [MAX3232E](#)

NOTE: Qualified Version Definitions:

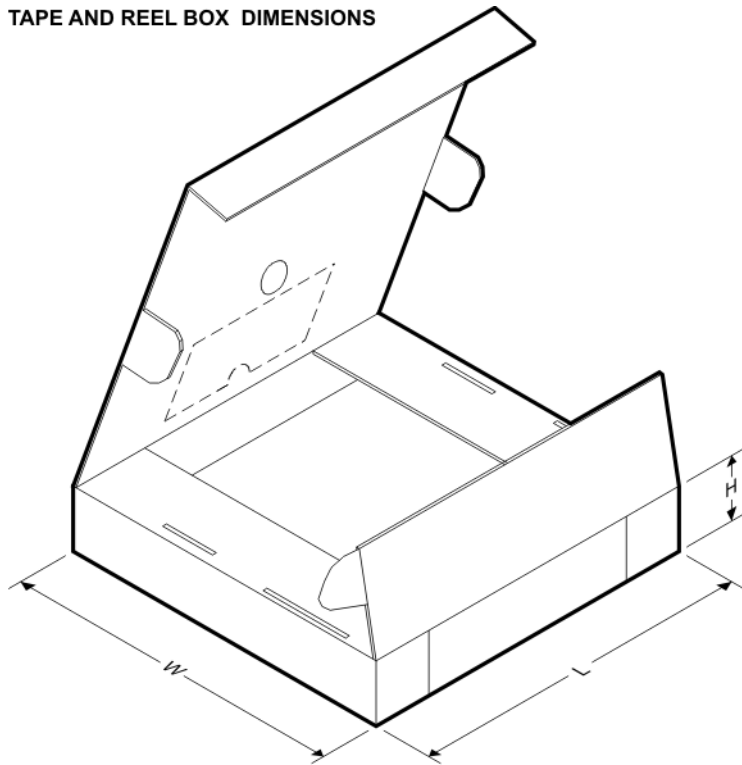
-
- Catalog - TI's standard catalog product

TAPE AND REEL INFORMATION


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
MAX3232EIPWRQ1	TSSOP	PW	16	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1

TAPE AND REEL BOX DIMENSIONS

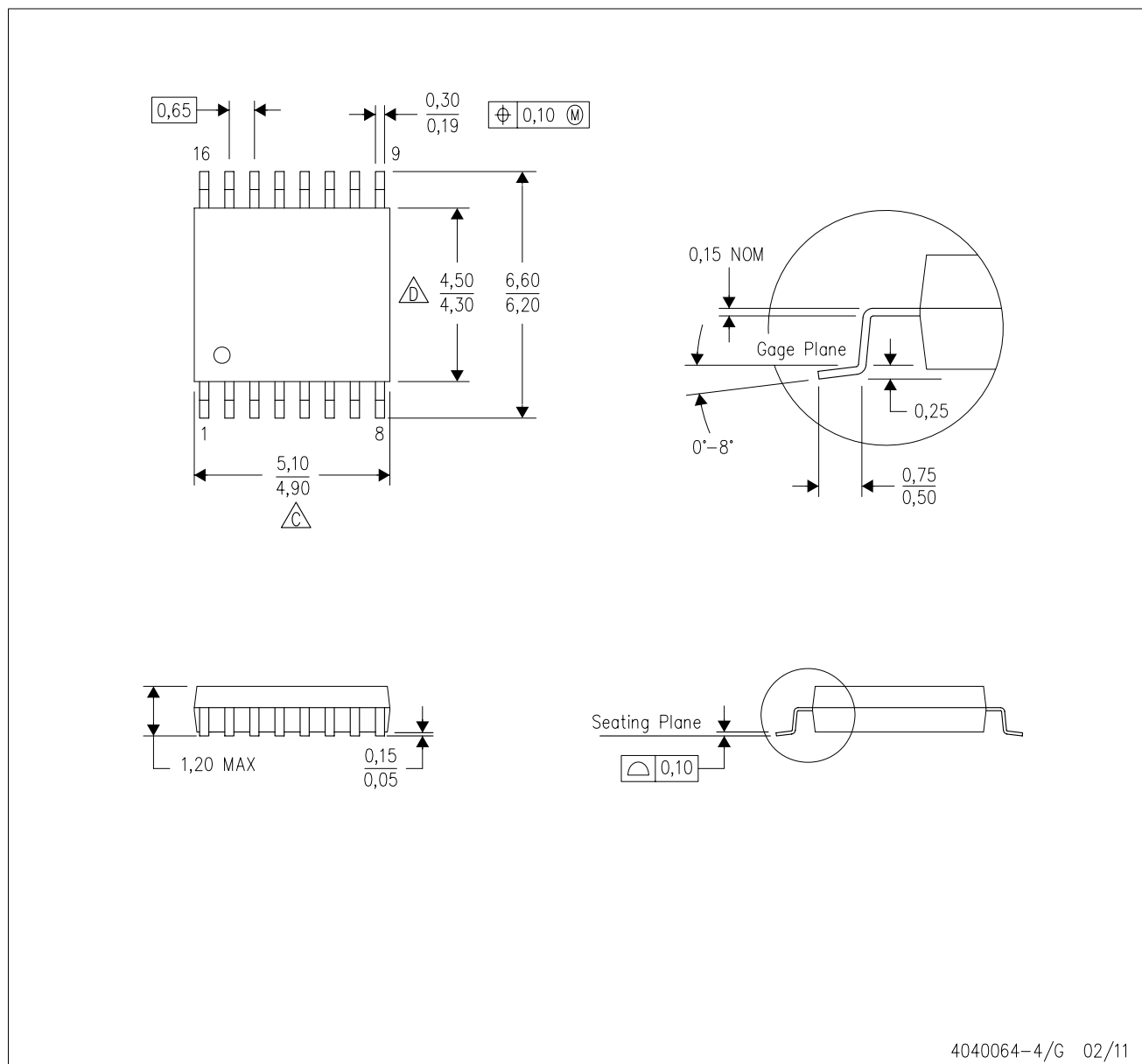


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
MAX3232EIPWRQ1	TSSOP	PW	16	2000	367.0	367.0	35.0

PW (R-PDSO-G16)

PLASTIC SMALL OUTLINE

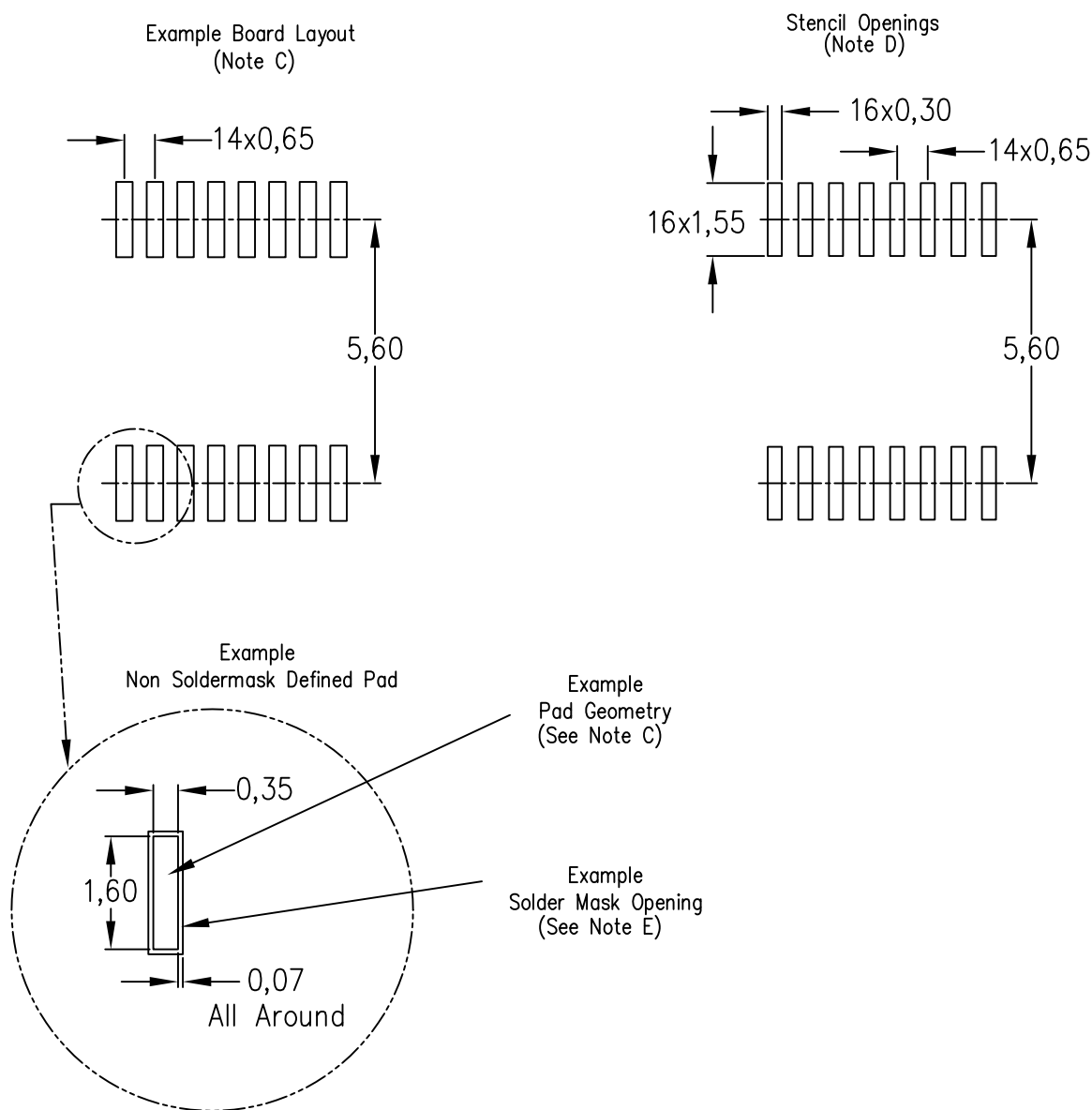


4040064-4/G 02/11

- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
 - B. This drawing is subject to change without notice.
 - C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
 - D. Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
 - E. Falls within JEDEC MO-153

PW (R-PDSO-G16)

PLASTIC SMALL OUTLINE



4211284-3/F 12/12

- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Publication IPC-7351 is recommended for alternate designs.
 - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

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